Call:
Factories of the Future 12
Industrial technologies for advanced joining and assembly processes for multi-materials

Proposal:
Hi-RAMP
High Reliability Assembly and Multi–material Processing.

Project Focus:
Advanced electronic components comprised of multi-materials.
These are impacted by buried joining defects between layers:
- voids
- delamination.

HI-RAMP will improve YIELDS:
Automated, non-destructive detection of buried defects
In line within the production process.

Goals:
Improve material joining processes
Improve production yields.

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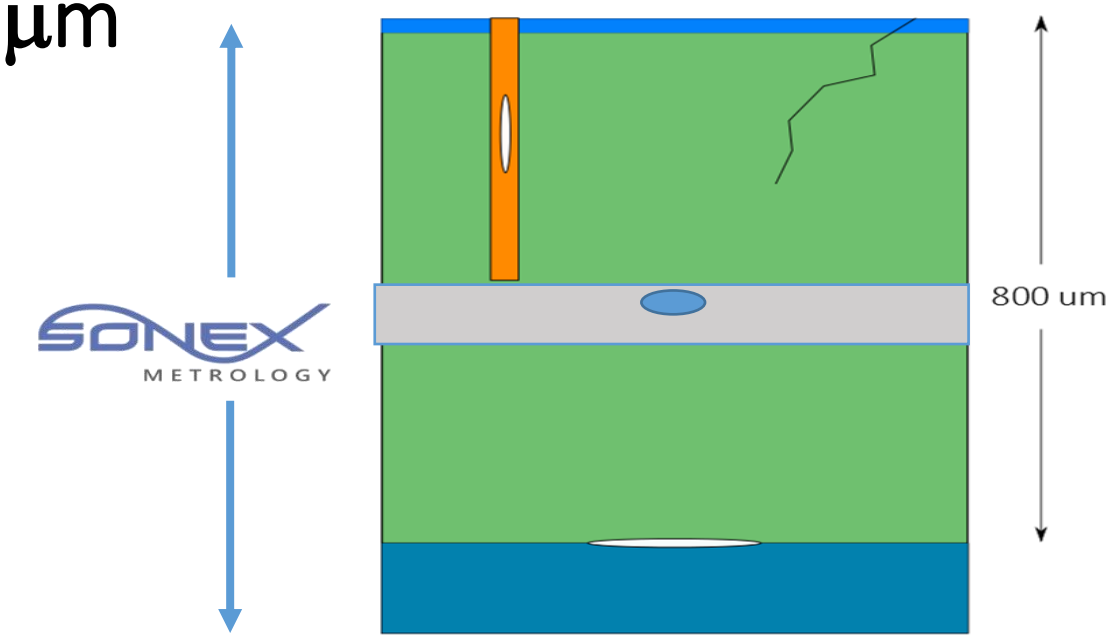
DCU

Innovation: Photoacoustic in line imaging through optically opaque materials to 800 µm



Current applications

- Delamination (tape, pad, wafer)
- Metal Voiding
- Buried micro-fractures

Application roadmap

- Film Thickness Measurements
- Film Uniformity Measurements
- Bio electronics

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Consortium

We have:

NDT Sensor Engine, End-User, Optics, Correlation, Dissemination.

We need:

Surface Conditioning, VCSEL Lasers, Simulation Software.

For more information on consortium or Sonex's sensor

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